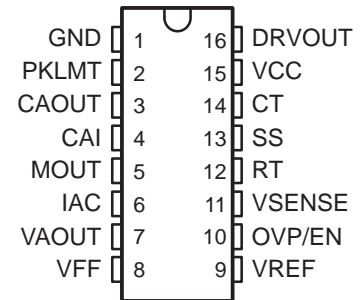


- Controls Boost Preregulator to Near-Unity Power Factor
- Limits Line Distortion
- World Wide Line Operation
- Over-Voltage Protection
- Accurate Power Limiting
- Average Current Mode Control
- Improved Noise Immunity
- Improved Feed-Forward Line Regulation
- Leading Edge Modulation
- 150- μ A Typical Start-Up Current
- Low-Power BiCMOS Operation
- 12-V to 17-V Operation

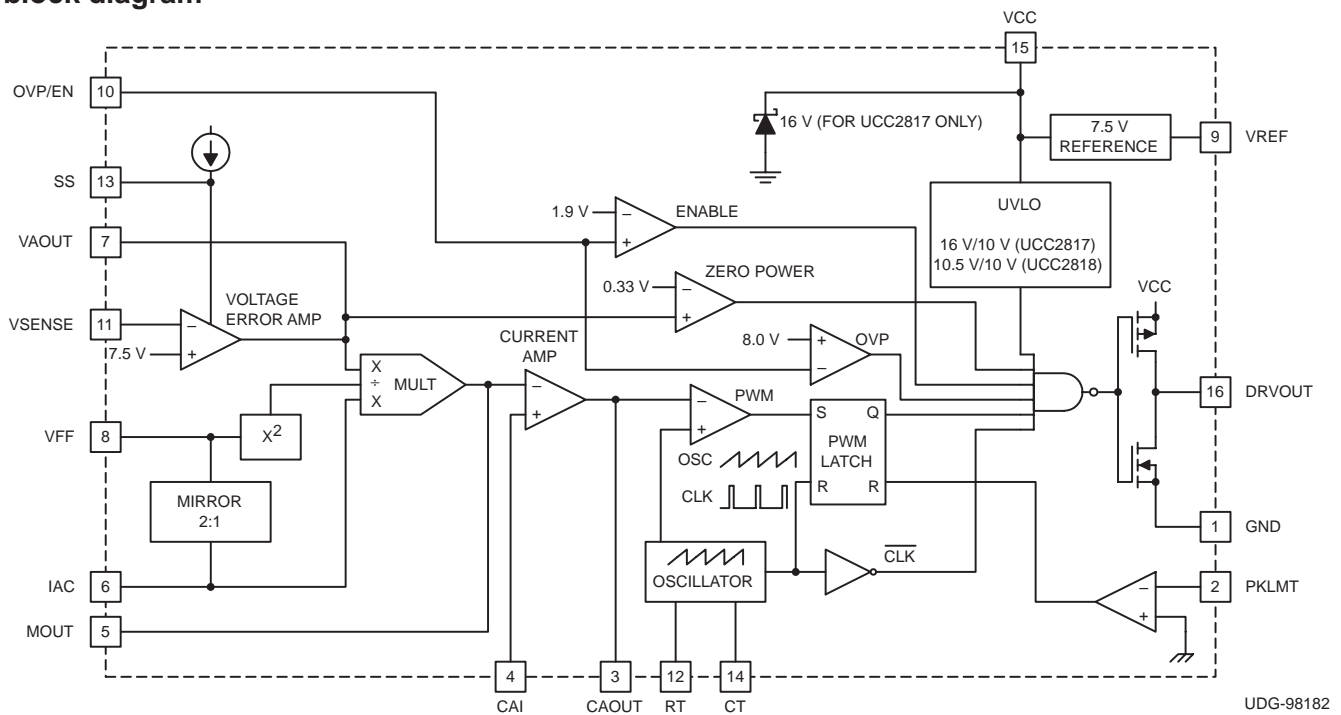
D, DW, and N PACKAGES
(TOP VIEW)



description

The UCCx817/18 family provides all the functions necessary for active power factor corrected preregulators. The controller achieves near unity power factor by shaping the ac input line current waveform to correspond to that of the ac input line voltage. Average current mode control maintains stable, low distortion sinusoidal line current.

block diagram



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



UCC2817, UCC2818, UCC3817, UCC3818 BiCMOS POWER FACTOR PREREGULATOR

SLUS395C - FEBRUARY 2000 - REVISED AUGUST 2000

description (continued)

Designed in Texas Instrument's BiCMOS process, the UCC2817/UCC2818 offers new features such as lower start-up current, lower power dissipation, overvoltage protection, a shunt UVLO detect circuitry, a leading-edge modulation technique to reduce ripple current in the bulk capacitor and an improved, low-offset (± 2 mV) current amplifier to reduce distortion at light load conditions.

UCC2817 offers an on-chip shunt regulator with low start-up current, suitable for applications utilizing a bootstrap supply. UCC2818 is intended for applications with a fixed supply (VCC).

Available in the 16-pin D, DW, and N packages.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage VCC	18 V
Gate drive current, continuous	0.2 A
Gate drive current	1.2 A
Input voltage, CAI, MOUT, SS	8 V
Input voltage, PKLMT	5 V
Input voltage, VSENSE, OVP/EN	10 V
Input current, RT, IAC, PKLMT	10 mA
Maximum negative voltage, DRVOUT, PKLMT, MOUT	-0.5 V
Power dissipation	1 W

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

AVAILABLE OPTIONS

T _J	PACKAGE DEVICES					
	D PACKAGE		DW PACKAGE		N PACKAGE	
	ON-CHIP SHUNT REGULATOR	FIXED SUPPLY (VCC)	ON-CHIP SHUNT REGULATOR	FIXED SUPPLY (VCC)	ON-CHIP SHUNT REGULATOR	FIXED SUPPLY (VCC)
-40°C to 85°C	UCC2817D	UCC2818D	UCC2817DW	UCC2818DW	UCC2817N	UCC2818N
0°C to 70°C	UCC3817D	UCC3818D	UCC3817DW	UCC3818DW	UCC3817N	UCC3818N

electrical characteristics, T_A = 0°C to 70°C for the UCC3817 and T_A = -40°C to 85°C for the UCC2817, T_A = T_J, VCC = 12 V, R_T = 22 kΩ, C_T = 330 pF, (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current Section					
Supply current, off	VCC = (VCC turn-on threshold - 0.3 V)		150	300	μA
Supply current, on	VCC = 12 V, No load on DRVOUT	2	4	6	mA
UVLO Section					
VCC turn-on threshold (UCCx817)		15.4	16	16.6	V
UVLO hysteresis (UCCx817)		5.8	6.3		V
Maximum shunt voltage (UCCx817)	I _{VCC} = 10 mA	15.4	17	17.5	V
VCC turn-on threshold (UCCx818)		9.7	10.2	10.8	V
VCC turn-off threshold (UCCx818)		9.4	9.7		V
UVLO hysteresis (UCCx818)		0.3	0.5		V



UCC2817, UCC2818, UCC3817, UCC3818 BiCMOS POWER FACTOR PREREGULATOR

SLUS395C - FEBRUARY 2000 - REVISED AUGUST 2000

electrical characteristics, $T_A = 0^\circ\text{C}$ to 70°C for the UCC3817 and $T_A = -40^\circ\text{C}$ to 85°C for the UCC2817, $T_A = T_J$, $V_{CC} = 12\text{ V}$, $R_T = 22\text{ k}\Omega$, $C_T = 330\text{ pF}$, (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Voltage Amplifier Section					
Input voltage	$T_A = 0^\circ\text{C}$ to 70°C	7.387	7.5	7.613	V
	$T_A = -40^\circ\text{C}$ to 85°C	7.369	7.5	7.631	V
V_{SENSE} bias current	$V_{SENSE} = V_{REF}$, $V_{AOUT} = 2.5\text{ V}$		50	200	nA
Open loop gain	$V_{AOUT} = 2\text{ V}$ to 5 V	50	90		dB
High-level output voltage	$I_L = -150\text{ }\mu\text{A}$	5.3	5.5	5.6	V
Low-level output voltage	$I_L = 150\text{ }\mu\text{A}$	0	50	150	mV
Over Voltage Protection and Enable Section					
Over voltage reference		$V_{REF} + 0.48$	$V_{REF} + 0.50$	$V_{REF} + 0.52$	V
Hysteresis		300	500	600	mV
Enable threshold		1.7	1.9	2.1	V
Enable hysteresis		0.1	0.2	0.3	V
Current Amplifier Section					
Input offset voltage	$V_{CM} = 0\text{ V}$, $V_{CAOUT} = 3\text{ V}$	-2	0	2	mV
Input bias current	$V_{CM} = 0\text{ V}$, $V_{CAOUT} = 3\text{ V}$		-50	-100	nA
Input offset current	$V_{CM} = 0\text{ V}$, $V_{CAOUT} = 3\text{ V}$		25	100	nA
Open loop gain	$V_{CM} = 0\text{ V}$, $V_{CAOUT} = 2\text{ V}$ to 5 V	90			dB
Common-mode rejection ratio	$V_{CM} = 0\text{ V}$ to 1.5 V , $V_{CAOUT} = 3\text{ V}$	60	80		dB
High-level output voltage	$I_L = -120\text{ }\mu\text{A}$	5.6	6.5	6.8	V
Low-level output voltage	$I_L = 1\text{ mA}$	0.1	0.2	0.5	V
Gain bandwidth product	See Note 1		2.5		MHz
Voltage Reference Section					
Input voltage	$T_A = 0^\circ\text{C}$ to 70°C	7.387	7.5	7.613	V
	$T_A = -40^\circ\text{C}$ to 85°C	7.369	7.5	7.631	V
Load regulation	$I_{REF} = 1\text{ mA}$ to 2 mA	0		10	mV
Line regulation	$V_{CC} = 10.8\text{ V}$ to 15 V , See Note 2	0		10	mV
Short-circuit current	$V_{REF} = 0\text{ V}$	-20	-25	-50	mA
Oscillator Section					
Initial accuracy	$T_A = 25^\circ\text{C}$	85	100	115	kHz
Voltage stability	$V_{CC} = 10.8\text{ V}$ to 15 V	-1		1	%
Total variation	Line, temp	80		120	kHz
Ramp peak voltage		4.5	5	5.5	V
Ramp amplitude voltage (peak to peak)		3.5	4	4.5	V
Peak Current Limit Section					
PKLMT reference voltage		-15		15	mV
PKLMT propagation delay		150	350	500	ns

NOTES: 1. Ensured by design, 100% production tested.
2. Reference variation for $V_{CC} < 10.8\text{ V}$ is shown in Figure 8.

UCC2817, UCC2818, UCC3817, UCC3818 BiCMOS POWER FACTOR PREREGULATOR

SLUS395C - FEBRUARY 2000 - REVISED AUGUST 2000

electrical characteristics, $T_A = 0^\circ\text{C}$ to 70°C for the UCC3817 and $T_A = -40^\circ\text{C}$ to 85°C for the UCC2817, $T_A = T_J$, $V_{CC} = 12\text{ V}$, $R_T = 22\text{ k}\Omega$, $C_T = 330\text{ pF}$, (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Multiplier Section					
High line, low power	$I_{AC} = 500\ \mu\text{A}$, $V_{FF} = 4.7\text{ V}$, $VA_{OUT} = 1.25\text{ V}$	0	-6	-20	μA
High line, high power	$I_{AC} = 500\ \mu\text{A}$, $V_{FF} = 4.7\text{ V}$, $VA_{OUT} = 5\text{ V}$	-75	-90	-110	μA
Low line, low power	$I_{AC} = 150\ \mu\text{A}$, $V_{FF} = 1.4\text{ V}$, $VA_{OUT} = 1.25\text{ V}$	-10	-19	-50	μA
Low line, high power	$I_{AC} = 150\ \mu\text{A}$, $V_{FF} = 1.4\text{ V}$, $VA_{OUT} = 5\text{ V}$	-260	-300	-360	μA
IAC limited	$I_{AC} = 150\ \mu\text{A}$, $V_{FF} = 1.3\text{ V}$, $VA_{OUT} = 5\text{ V}$	-250	-300	-400	μA
Gain constant (K)	$I_{AC} = 300\ \mu\text{A}$, $V_{FF} = 3\text{ V}$, $VA_{OUT} = 2.5\text{ V}$	0.5	1	1.5	1/V
Zero current	$I_{AC} = 150\ \mu\text{A}$, $V_{FF} = 1.4\text{ V}$, $VA_{OUT} = 0.25\text{ V}$		0	-2	μA
	$I_{AC} = 500\ \mu\text{A}$, $V_{FF} = 4.7\text{ V}$, $VA_{OUT} = 0.25\text{ V}$		0	-2	μA
	$I_{AC} = 500\ \mu\text{A}$, $V_{FF} = 4.7\text{ V}$, $VA_{OUT} = 0.5\text{ V}$		0	-3	μA
Power limit	$I_{AC} = 150\ \mu\text{A}$, $V_{FF} = 1.4\text{ V}$, $VA_{OUT} = 5\text{ V}$	-360	-420	-500	μW
Feed-Forward Section					
VFF output current	$I_{AC} = 300\ \mu\text{A}$	-140	-150	-160	μA
Soft Start Section					
SS charge current		-6	-10	-16	μA
Gate Driver Section					
Pullup resistance	$I_O = -100\text{ mA}$		5	12	Ω
Pulldown resistance	$I_O = 100\text{ mA}$		2	10	Ω
Output rise time	$C_L = 1\text{ nF}$, $R_L = 10\ \Omega$		25	50	ns
Output fall time	$C_L = 1\text{ nF}$, $R_L = 10\ \Omega$		10	50	ns
Maximum duty cycle		93	95	100	%
Zero Power Section					
Zero power comparator threshold	Measured on VA_{OUT}	0.20	0.33	0.50	V

pin descriptions

CAI: (current amplifier non-inverting input) This input and the inverting input (MOUT) remain functional down to and below GND.

CAOUT: (current amplifier output) This is the output of a wide bandwidth operational amplifier that senses line current and commands the PFC pulse-width modulator (PWM) to force the correct current.

CT: (oscillator timing capacitor) A capacitor from CT to GND sets the PWM oscillator frequency according to:

$$f = \left(\frac{0.725}{RT \times CT} \right)$$

The lead from the oscillator timing capacitor to GND should be as short and direct as possible.

DRVOUT: (gate drive) The output drive for the PFC stage is a totem-pole MOSFET gate driver on DRVOUT. Use a series gate resistor to prevent interaction between the gate impedance and the output driver that might cause the DRVOUT to overshoot excessively. See characteristic curve (Figure 13) to determine minimum required gate resistor value. Some overshoot of the DRVOUT output is always expected when driving a capacitive load.

GND: (ground) All voltages measured with respect to ground. VCC and REF should be bypassed directly to GND with a 0.1- μF or larger ceramic capacitor.



pin descriptions (continued)

IAC: (input ac current) This input to the analog multiplier is a current. The multiplier is tailored for very low distortion from this current input (I_{IAC}) to multiplier output. The recommended maximum I_{IAC} is 500 μ A.

MOUT: (multiplier output and current amplifier inverting input) The output of the analog multiplier and the inverting input of the current amplifier are connected together at MOUT. As the multiplier output is a current, this is a high-impedance input so the amplifier can be configured as a differential amplifier. This configuration improves noise immunity and allows for the leading-edge modulation operation. The multiplier is limited to $(2 \times I_{IAC})$. The multiplier output current is given by the equation:

$$I_{MOUT} = \frac{I_{IAC} \times (V_{VAOUT} - 1)}{V_{VFF}^2 \times K}$$

Where $K = \frac{1}{V}$ is the multiplier gain constant.

OVP/EN: (over-voltage/enable) A window comparator input that disables the output driver if the boost output is a programmed level above nominal or disables both the PFC output driver and resets SS if pulled below 1.9 V (typ).

PKLMT: (PFC peak current limit) The threshold for peak limit is 0 V. Use a resistor divider from the negative side of the current sense resistor to VREF to level shift this signal to a voltage level defined by the value of the sense resistor and the peak current limit. Peak current limit is reached when PKLMT voltage falls below 0 V.

RT: (oscillator charging current) A resistor from RT to GND is used to program oscillator charging current. A resistor between 10 k Ω and 100 k Ω is recommended.

SS: (soft-start) V_{SS} is at ground for V_{VCC} low conditions. When enabled, SS charges an external capacitor with a current source. This voltage is used as the voltage error signal during start-up, enabling the PWM duty cycle to increase slowly. In the event of a V_{VCC} dropout the OVP/EN is forced below 1.9 V (typ), SS quickly discharges to disable the PWM.

Note: In an open-loop test circuit, grounding the SS pin does not ensure 0% duty cycle. Please see the application section for details.

VAOUT: (voltage amplifier output) This is the output of the operational amplifier that regulates output voltage. The voltage amplifier output is internally limited to approximately 5.5 V to prevent overshoot.

VCC: (positive supply voltage) Connect to a stable source of at least 20 mA between 10 V and 17 V for normal operation. Bypass VCC directly to GND to absorb supply current spikes required to charge external MOSFET gate capacitances. To prevent inadequate gate drive signals, the output devices are inhibited unless V_{VCC} exceeds the upper under-voltage lockout voltage threshold and remains above the lower threshold.

VFF: (feed-forward signal) RMS signal generated at this pin by mirroring I_{IAC} into a single pole external filter.

$$R_{VFF} = \frac{V_{VFF(max)}}{\frac{I_{IAC(max)}}{2\sqrt{2}} \times 0.9}$$

VSENSE: (voltage amplifier inverting input) This is normally connected to a compensation network and to the boost converter output through a divider network.

VREF: (voltage reference output) VREF is the output of an accurate 7.5-V voltage reference. This output is capable of delivering 20 mA to peripheral circuitry and is internally short-circuit current limited. VREF is disabled and remains at 0 V when V_{VCC} is below the UVLO threshold. Bypass VREF to GND with a 0.1- μ F or larger ceramic capacitor for best stability. Please refer to Figures 8 and 9 for VREF line and load regulation characteristics.

UCC2817, UCC2818, UCC3817, UCC3818 BiCMOS POWER FACTOR PREREGULATOR

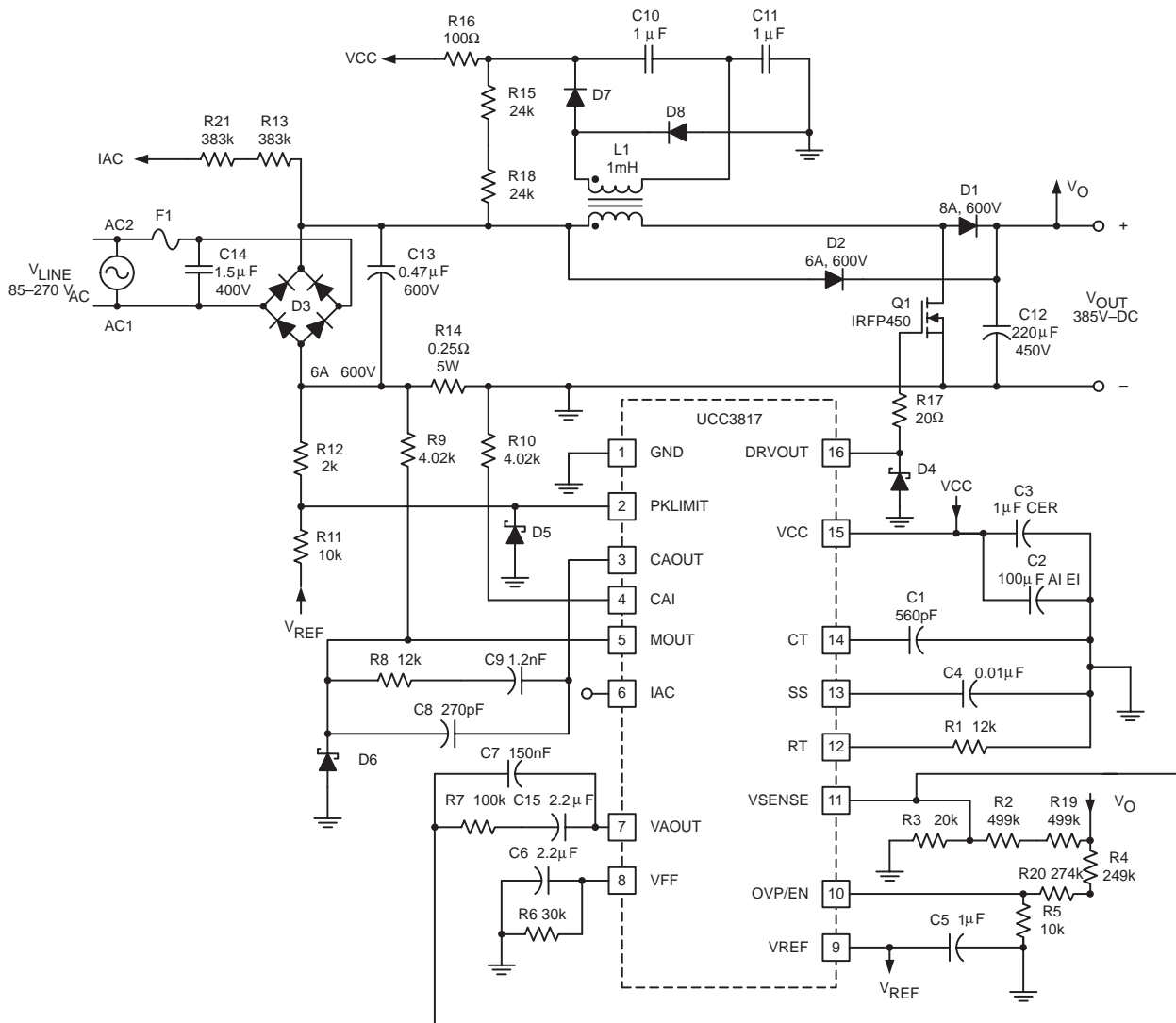
SLUS395C - FEBRUARY 2000 - REVISED AUGUST 2000

APPLICATION INFORMATION

The UCC3817 is a BiCMOS average current mode boost controller for high power factor, high efficiency preregulator power supplies. Figure 1 shows the UCC3817 in a 250-W PFC preregulator circuit. Off-line switching power converters normally have an input current that is not sinusoidal. The input current waveform has a high harmonic content because current is drawn in pulses at the peaks of the input voltage waveform. An active power factor correction circuit programs the input current to follow the line voltage, forcing the converter to look like a resistive load to the line. A resistive load has 0° phase displacement between the current and voltage waveforms. Power factor can be defined in terms of the phase angle between two sinusoidal waveforms of the same frequency:

$$PF = \cos \Theta$$

Therefore, a purely resistive load would have a power factor of 1. In practice, power factors of 0.999 with THD (total harmonic distortion) less than 3% are possible with a well-designed circuit. Following guidelines are provided to design PFC boost converters using the UCC3817.



UDG-98183

Figure 1. Typical Application Circuit



APPLICATION INFORMATION

power stage

L_{BOOST} : The boost inductor value is determined by:

$$L_{\text{BOOST}} = \frac{(V_{\text{IN}(\text{min})} \times D)}{(\Delta I \times f_s)}$$

Where D is the duty cycle, ΔI is the inductor ripple current and f_s is the switching frequency. For the example circuit a switching frequency of 100 kHz, a ripple current of 875 mA, a maximum duty cycle of 0.688 and a minimum input voltage of 85 V_{RMS} gives us a boost inductor value of about 1 mH. The values used in this equation are at the peak of low line, where the inductor current and its ripple are at a maximum.

C_{OUT} : Two main criteria, the capacitance and the voltage rating, dictate the selection of the output capacitor. The value of capacitance is determined by the hold-up time required for supporting the load after input ac voltage is removed. Hold-up is the amount of time that the output stays in regulation after the input has been removed. For this circuit, the desired hold-up time is approximately 16 ms. Expressing the capacitor value in terms of output power, output voltage, and hold-up time gives the equation:

$$C_{\text{OUT}} = \frac{(2 \times P_{\text{OUT}} \times \Delta t)}{(V_{\text{OUT}}^2 - V_{\text{OUT}(\text{min})}^2)}$$

In practice, the calculated minimum capacitor value may be inadequate because output ripple voltage specifications limit the amount of allowable output capacitor ESR. Attaining a sufficiently low value of ESR often necessitates the use of a much larger capacitor value than calculated. The amount of output capacitor ESR allowed can be determined by dividing the maximum specified output ripple voltage by the inductor ripple current. In this design hold-up time was the dominant determining factor and a 220- μ F, 450-V capacitor was chosen for the output voltage level of 385 VDC at 250 W.

power switch selection

As in any power supply design, tradeoffs between performance, cost and size have to be made. When selecting a power switch, it can be useful to calculate the total power dissipation in the switch for several different devices at the switching frequencies being considered for the converter. Total power dissipation in the switch is the sum of switching loss and conduction loss. Switching losses are the combination of the gate charge loss, C_{OSS} loss and turn-on and turn-off losses:

$$P_{\text{GATE}} = Q_{\text{GATE}} \times V_{\text{GATE}} \times f_s$$

$$P_{\text{COSS}} = \frac{1}{2} \times C_{\text{OSS}} \times V_{\text{OFF}}^2 \times f_s$$

$$P_{\text{ON}} + P_{\text{OFF}} = \frac{1}{2} \times V_{\text{OFF}} \times I_L \times (t_{\text{ON}} + t_{\text{OFF}}) \times f_s$$

where Q_{GATE} is the total gate charge, V_{GATE} is the gate drive voltage, f_s is the clock frequency, C_{OSS} is the drain source capacitance of the MOSFET, t_{ON} and t_{OFF} are the switching times (estimated using device parameters R_{GATE} , Q_{GD} and V_{TH}) and V_{OFF} is the voltage across the switch during the off time, in this case $V_{\text{OFF}} = V_{\text{OUT}}$.

UCC2817, UCC2818, UCC3817, UCC3818 BiCMOS POWER FACTOR PREREGULATOR

SLUS395C - FEBRUARY 2000 - REVISED AUGUST 2000

APPLICATION INFORMATION

power switch selection (continued)

Conduction loss is calculated as the product of the $R_{DS(on)}$ of the switch (at the worst case junction temperature) and the square of RMS current:

$$P_{COND} = R_{DS(on)} \times K \times I_{RMS}^2$$

where K is the temperature factor found in the manufacturer's $R_{DS(on)}$ vs. junction temperature curves.

Calculating these losses and plotting against frequency gives a curve that enables the designer to determine either which manufacturer's device has the best performance at the desired switching frequency, or which switching frequency has the least total loss for a particular power switch. For this design example an IRFP450 HEXFET from International Rectifier was chosen because of its low $R_{DS(on)}$ and its V_{DSS} rating. The IRFP450's $R_{DS(on)}$ of 40 m Ω and the maximum V_{DSS} of 500 V made it an ideal choice. An excellent review of this procedure can be found in the Unitrode Power Supply Design Seminar SEM1200, Topic 6, Design Review: 140 W, [Multiple Output High Density DC/DC Converter].

softstart

The softstart circuitry is used to prevent overshoot of the output voltage during start up. This is accomplished by bringing up the voltage amplifier's output (V_{VAOUT}) slowly which allows for the PWM duty cycle to increase slowly. Please use the following equation to select a capacitor for the softstart pin.

In this example t_{DELAY} is equal to 7.5 ms, which would yield a C_{SS} of 10 nF.

$$C_{SS} = \frac{10 \mu A \times t_{DELAY}}{7.5 V}$$

In an open-loop test circuit, shorting the softstart pin to ground does not ensure 0% duty cycle. This is due to the current amplifier's input offset voltage, which could force the current amplifier output high or low depending on the polarity of the offset voltage. However, in the typical application there is sufficient amount of inrush and bias current to overcome the current amplifier's offset voltage.

multiplier

The output of the multiplier of the UCC3817 is a signal representing the desired input line current. It is an input to the current amplifier, which programs the current loop to control the input current to give high power factor operation. As such, the proper functioning of the multiplier is key to the success of the design. The inputs to the multiplier are VAOUT, the voltage amplifier error signal, I_{IAC} , a representation of the input rectified ac line voltage, and an input voltage feedforward signal, V_{VFF} . The output of the multiplier, I_{MOUT} , can be expressed:

$$I_{MOUT} = I_{IAC} \times \frac{(V_{VAOUT} - 1)}{K \times V_{VFF}^2}$$

where K is a constant typically equal to $\frac{1}{V}$.

APPLICATION INFORMATION

multiplier (continued)

The I_{IAC} signal is obtained through a high-value resistor connected between the rectified ac line and the IAC pin of the UCC3817. This resistor is sized to give the maximum I_{IAC} current at high line. For this device, the maximum I_{IAC} current is about 500 μA . A higher current than this can drive the multiplier out of its linear range. A smaller current level is functional, but noise can become an issue, especially at low input line. Assuming a universal line operation of 85 VAC to 265 VAC gives a resistor value of 750 k Ω . Because of voltage rating constraints of standard 1/4 W resistors, use a combination of lower value resistors connected in series to give the 750 k Ω value and distribute the high voltage across two or more resistors.

The current through the I_{IAC} resistor is mirrored internally to the VFF pin where it is filtered to produce a voltage feedforward signal proportional to line voltage and free of a 120-Hz ripple component. This second harmonic ripple component at the VFF pin is one of the major contributors to harmonic distortion in the system, so adequate filtering is crucial. Refer to Unitrode Power Supply Design Seminar, SEM-700 Topic 7, [*Optimizing the Design of a High Power Factor Preregulator.*] Assuming that an allocation of 1.5% total harmonic distortion from this input is allowed, and that the second harmonic ripple is 66% of the input ac line voltage, the amount of attenuation required by this filter is:

$$\frac{1.5\%}{66\%} \text{ or } 0.022$$

A ripple frequency (f_R) of 120 Hz and an attenuation of 0.022 gives us a single-pole filter with:

$$f_p = 120 \text{ Hz} \times 0.022 = 2.6 \text{ Hz}$$

The range of this input to the multiplier should be 0.5 V to 5.5 V over the line input range. Therefore the filter resistor should be sized accordingly. Maximum I_{IAC} current is 500 μA , mirrored 2:1 to VFF, becomes 250 μA . The dc output is 90% of the RMS value of this half sine wave, or 159 μA . So the filter resistor should be equal to the voltage swing of the input to the multiplier divided by the dc current or:

$$\frac{5 \text{ V}}{159 \mu\text{A}} = 31.44 \text{ k}\Omega$$

Select a 30 k Ω resistor for a standard value. Solving for the capacitor value:

$$C_{VFF} = \frac{1}{2 \pi (30 \text{ k}\Omega)(2.6 \text{ Hz})} \approx 2.2 \mu\text{F}$$

This results in a single-pole filter, which adequately attenuates the harmonic distortion and also meets the dc requirement of the proper voltage swing across line conditions.

The R_{MOUT} resistor is sized to match the maximum current through the sense resistor to the maximum multiplier current. The maximum multiplier current, or $I_{MOUT(max)}$, can be determined by the equation:

$$I_{MOUT(max)} = \frac{I_{IAC@V_{IN(min)}} \times (V_{VAOUT(max)} - 1\text{V})}{K \times V_{VFF(min)}^2}$$

$I_{MOUT(max)}$ for this design is approximately 315 μA . The R_{MOUT} resistor can then be determined by:

$$R_{MOUT} = \frac{V_{RSENSE}}{I_{MOUT(max)}}$$

In this example R_{MOUT} is equal to 3.91 k Ω .

APPLICATION INFORMATION

voltage loop

The second major source of harmonic distortion is the ripple on the output capacitor at the second harmonic of the line frequency. This ripple is fed back through the error amplifier and appears as a 3rd harmonic ripple at the input to the multiplier. The voltage loop must be compensated not just for stability but also to attenuate the contribution of this ripple to the total harmonic distortion of the system. (refer to Figure 2).

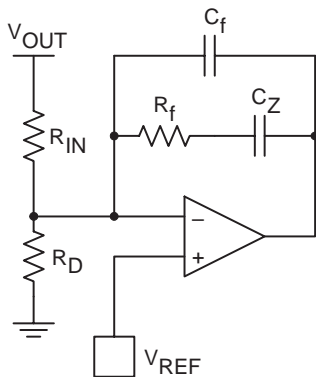


Figure 2. Voltage Amplifier Configuration

The gain of the voltage amplifier, G_{VA} , can be determined by first calculating the amount of ripple present on the output capacitor. The peak value of the second harmonic voltage is given by the equation:

$$V_{OPK} = \frac{P_{IN}}{(2\pi \times f_R \times C_{OUT} \times V_{OUT})}$$

In this example V_{OPK} is equal to 3.91 V. Assuming an allowable contribution of 0.75% (1.5% peak to peak) from the voltage loop to the total harmonic distortion budget we set the gain equal to:

$$G_{VA} = \frac{(\Delta V_{VAOUT})(0.015)}{V_{OPK}}$$

where ΔV_{VAOUT} is the effective output voltage range of the error amplifier (5 V for the UCC3817). The network needed to realize this filter is comprised of an input resistor, R_{IN} , and feedback components C_f , C_Z , and R_f . The value of R_{IN} is already determined because of its function as one half of a resistor divider from V_{OUT} feeding back to the voltage amplifier for output voltage regulation. In this case the value was chosen to be 1 MΩ. This high value was chosen to reduce power dissipation in the resistor. In practice, the resistor value would be realized by the use of two 500-kΩ resistors in series because of the voltage rating constraints of most standard 1/4-W resistors. The value of C_f is determined by the equation:

$$C_f = \frac{1}{(2\pi \times f_R \times G_{VA} \times R_{IN})}$$

APPLICATION INFORMATION

voltage loop (continued)

In this example C_f equals 150 nF. Resistor R_f sets the dc gain of the error amplifier and thus determines the frequency of the pole of the error amplifier. The location of the pole can be found by setting the gain of the loop equation to one and solving for the crossover frequency. The frequency, expressed in terms of input power, can be calculated by the equation:

$$f_{VI}^2 = \frac{P_{IN}}{\left((2\pi)^2 \times \Delta V_{VAOUT} \times V_{OUT} \times R_{IN} \times C_{OUT} \times C_f \right)}$$

f_{VI} for this converter is 10 Hz. A derivation of this equation can be found in the Unitrode Power Supply Design Seminar SEM1000, Topic 1, [A 250-kHz, 500-W Power Factor Correction Circuit Employing Zero Voltage Transitions].

Solving for R_f becomes:

$$R_f = \frac{1}{\left(2\pi \times f_{VI} \times C_f \right)}$$

or R_f equals 100 k Ω .

Due to the low output impedance of the voltage amplifier, capacitor C_Z was added in series with R_f to reduce loading on the voltage divider. To ensure the voltage loop crossed over at f_{VI} , C_Z was selected to add a zero at a 10th of f_{VI} . For this design a 2.2- μ F capacitor was chosen for C_Z . The following equation can be used to calculate C_Z .

$$C_Z = \frac{1}{2 \times \pi \times \frac{f_{VI}}{10} \times R_f}$$

current loop

The gain of the power stage is:

$$G_{ID}(s) = \frac{\left(V_{OUT} \times R_{SENSE} \right)}{\left(s \times L_{BOOST} \times V_P \right)}$$

R_{SENSE} has been chosen to give the desired differential voltage for the current sense amplifier at the desired current limit point. In this example, a current limit of 4 A and a reasonable differential voltage to the current amp of 1 V gives a R_{SENSE} value of 0.25 Ω . V_P in this equation is the voltage swing of the oscillator ramp, 4 V for the UCC3817. Setting the crossover frequency of the system to 1/10th of the switching frequency, or 10 kHz, requires a power stage gain at that frequency of 0.383. In order for the system to have a gain of 1 at the crossover frequency, the current amplifier needs to have a gain of $1/G_{PS}$ at that frequency. G_{EA} , the current amplifier gain is then:

$$G_{EA} = \frac{1}{G_{ID}} = \frac{1}{0.383} = 2.611$$

APPLICATION INFORMATION

current loop (continued)

R_1 is the R_{MOUT} resistor, previously calculated to be 3.9 k Ω . (refer to Figure 3). The gain of the current amplifier is R_f/R_1 , so multiplying R_1 by G_{EA} gives the value of R_f , in this case approximately 12 k Ω . Setting a zero at the crossover frequency and a pole at half the switching frequency completes the current loop compensation.

$$C_Z = \frac{1}{2 \times \pi \times R_f \times f_C}$$

$$C_P = \frac{1}{2 \times \pi \times R_f \times \frac{f_S}{2}}$$

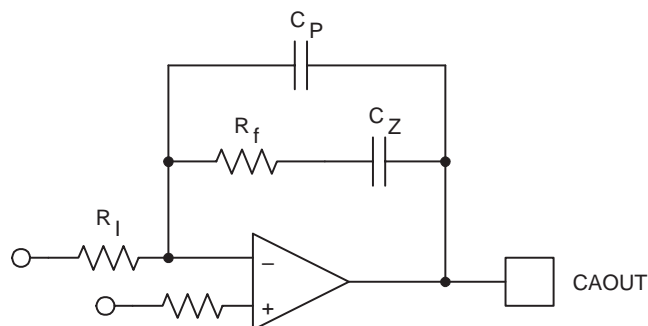


Figure 3. Current Loop Compensation

The UCC3817 current amplifier has the input from the multiplier applied to the inverting input. This change in architecture from previous Texas Instruments PFC controllers improves noise immunity in the current amplifier. It also adds a phase inversion into the control loop. The UCC3817 takes advantage of this phase inversion to implement leading-edge duty cycle modulation. Synchronizing a boost PFC controller to a downstream dc-to-dc controller reduces the ripple current seen by the bulk capacitor between stages, reducing capacitor size and cost and reducing EMI. This is explained in greater detail in a following section. The UCC3817 current amplifier configuration is shown in Figure 4.

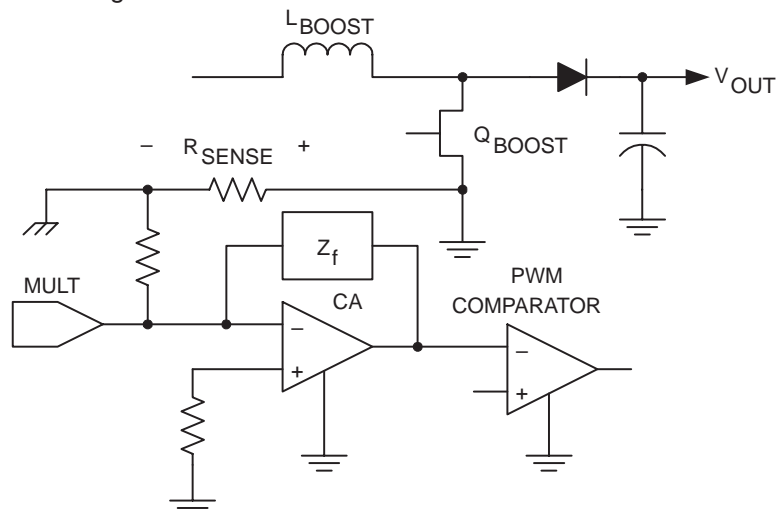


Figure 4. UCC3817 Current Amplifier Configuration

APPLICATION INFORMATION

start up

The UCC3818 version of the device is intended to have VCC connected to a 12-V supply voltage. The UCC3817 has an internal shunt regulator enabling the device to be powered from bootstrap circuitry as shown in the typical application circuit of Figure 1. The current drawn by the UCC3817 during undervoltage lockout, or start-up current, is typically 150 μ A. Once VCC is above the UVLO threshold, the device is enabled and draws 4 mA typically. A resistor connected between the rectified ac line voltage and the VCC pin provides current to the shunt regulator during power up. Once the circuit is operational the bootstrap winding of the inductor provides the VCC voltage. Sizing of the start-up resistor is determined by the start-up time requirement of the system design.

$$I_C = C \frac{\Delta V}{\Delta t}$$

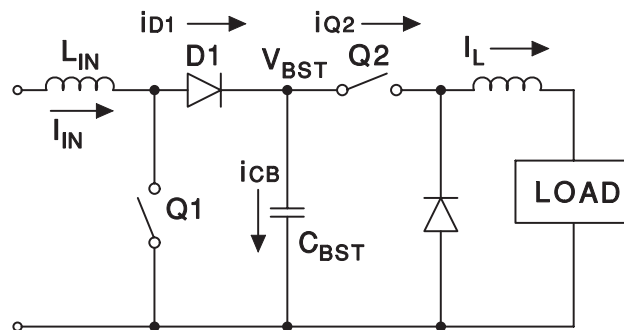
$$R = \frac{V_{RMS} \times (0.9)}{I_C}$$

Where I_C is the charge current, C is the total capacitance at the VCC pin, ΔV is the UVLO threshold and t is the allowed start-up time.

Assuming a 1 second allowed start-up time, a 16-V UVLO threshold, and a total VCC capacitance of 100 μ F, a resistor value of 51 k Ω is required at a low line input voltage of 85 V_{RMS} . The IC start-up current is sufficiently small as to be ignored in sizing the start-up resistor.

capacitor ripple reduction

For a power system where the PFC boost converter is followed by a dc-to-dc converter stage, there are benefits to synchronizing the two converters. In addition to the usual advantages such as noise reduction and stability, proper synchronization can significantly reduce the ripple currents in the boost circuit's output capacitor. Figure 5 helps illustrate the impact of proper synchronization by showing a PFC boost converter together with the simplified input stage of a forward converter. The capacitor current during a single switching cycle depends on the status of the switches Q1 and Q2 and is shown in Figure 6. It can be seen that with a synchronization scheme that maintains conventional trailing-edge modulation on both converters, the capacitor current ripple is highest. The greatest ripple current cancellation is attained when the overlap of Q1 offtime and Q2 ontime is maximized. One method of achieving this is to synchronize the turnon of the boost diode (D1) with the turnon of Q2. This approach implies that the boost converter's leading edge is pulse width modulated while the forward converter is modulated with traditional trailing edge PWM. The UCC3817 is designed as a leading edge modulator with easy synchronization to the downstream converter to facilitate this advantage. Table 1 compares the $I_{CB(rms)}$ for D1/Q2 synchronization as offered by UCC3817 vs. the $I_{CB(rms)}$ for the other extreme of synchronizing the turnon of Q1 and Q2 for a 200-W power system with a V_{BST} of 385 V.

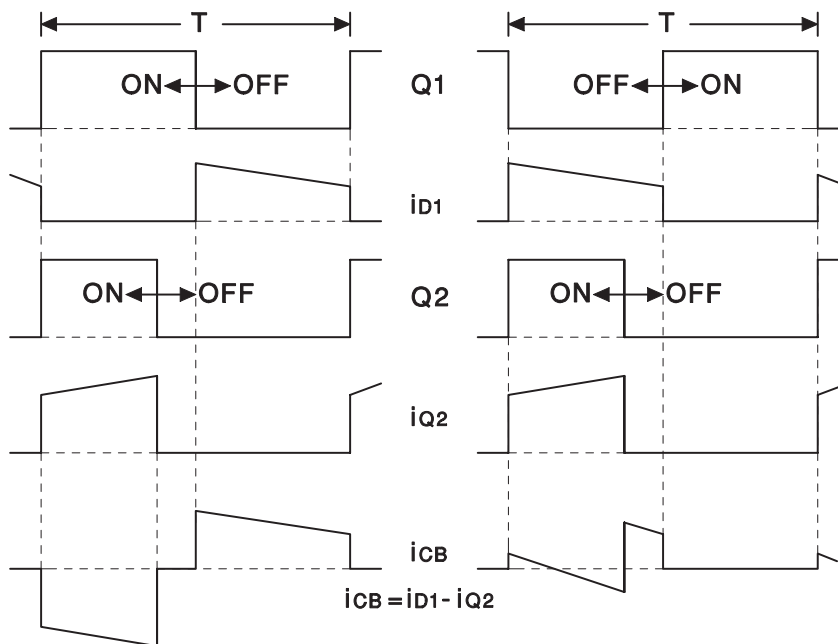


UDG-97130-1

Figure 5. Simplified Representation of a 2-Stage PFC Power Supply

APPLICATION INFORMATION

capacitor ripple reduction (continued)



UDG-97131

Figure 6. Timing Waveforms for Synchronization Scheme

Table 1. Effects of Synchronization on Boost Capacitor Current

	$V_{IN} = 85\text{ V}$		$V_{IN} = 120\text{ V}$		$V_{IN} = 240\text{ V}$	
	Q1/Q2	D1/Q2	Q1/Q2	D1/Q2	Q1/Q2	D1/Q2
D(Q2)						
0.35	1.491 A	0.835 A	1.341 A	0.663 A	1.024 A	0.731 A
0.45	1.432 A	0.93 A	1.276 A	0.664 A	0.897 A	0.614 A

Table 1 illustrates that the boost capacitor ripple current can be reduced by about 50% at nominal line and about 30% at high line with the synchronization scheme facilitated by the UCC3817. Figure 7 shows the suggested technique for synchronizing the UCC3817 to the downstream converter. With this technique, maximum ripple reduction as shown in Figure 6 is achievable. The output capacitance value can be significantly reduced if its choice is dictated by ripple current or the capacitor life can be increased as a result. In cost sensitive designs where holdup time is not critical, this is a significant advantage.

An alternative method of synchronization to achieve the same ripple reduction is possible. In this method, the turnon of Q1 is synchronized to the turnoff of Q2. While this method yields almost identical ripple reduction and maintains trailing edge modulation on both converters, the synchronization is much more difficult to achieve and the circuit can become susceptible to noise as the synchronizing edge itself is being modulated.

APPLICATION INFORMATION

capacitor ripple reduction (continued)

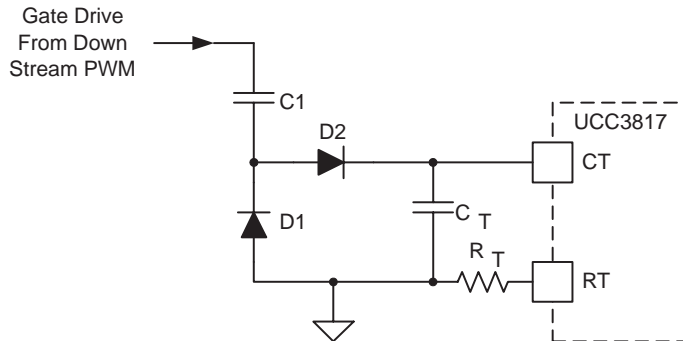


Figure 7. Synchronizing the UCC3817 to a Down-Stream Converter

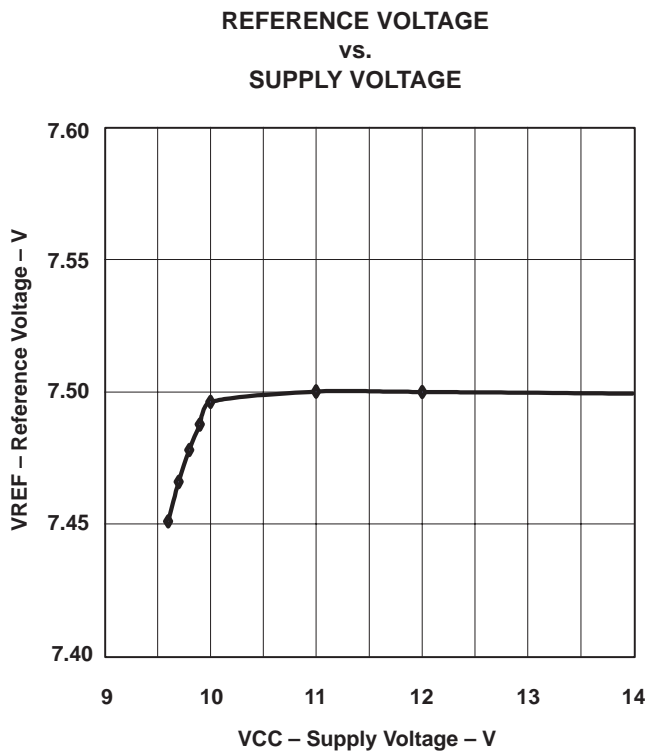


Figure 8

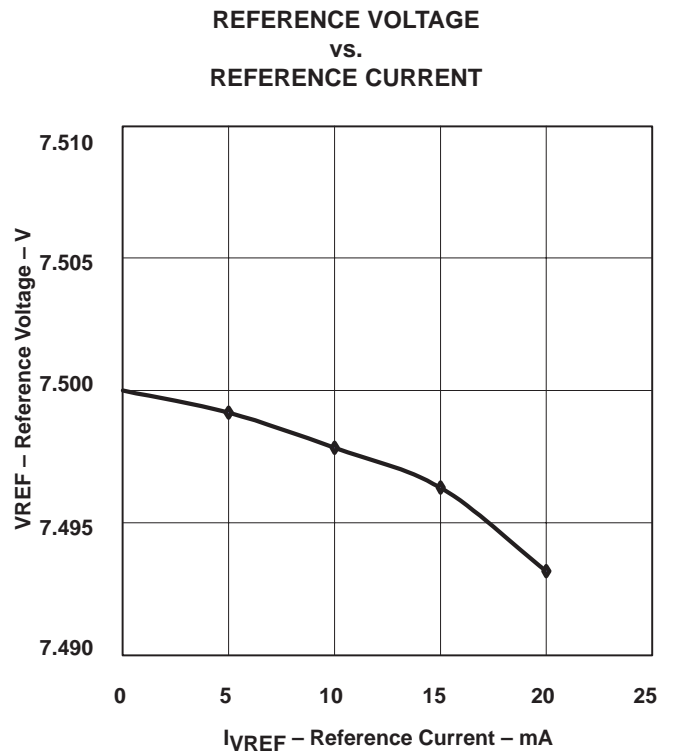


Figure 9

UCC2817, UCC2818, UCC3817, UCC3818 BiCMOS POWER FACTOR PREREGULATOR

SLUS395C - FEBRUARY 2000 - REVISED AUGUST 2000

APPLICATION INFORMATION

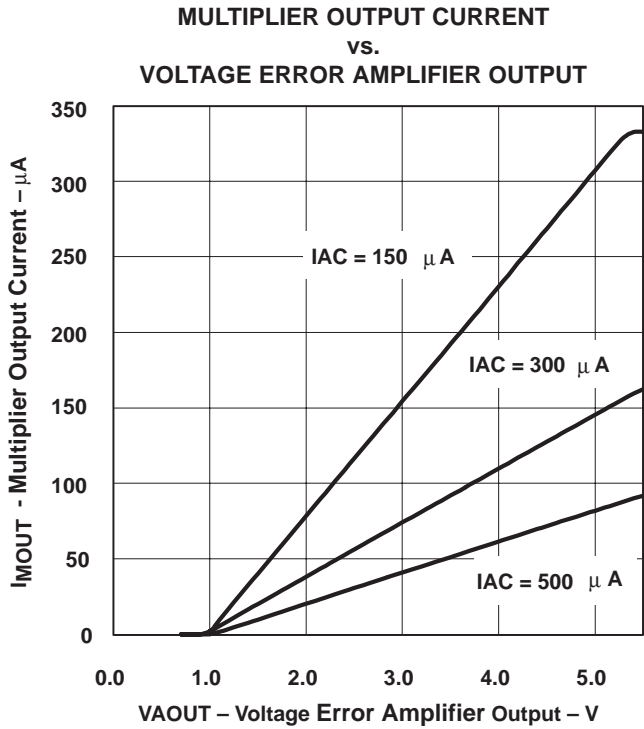


Figure 10

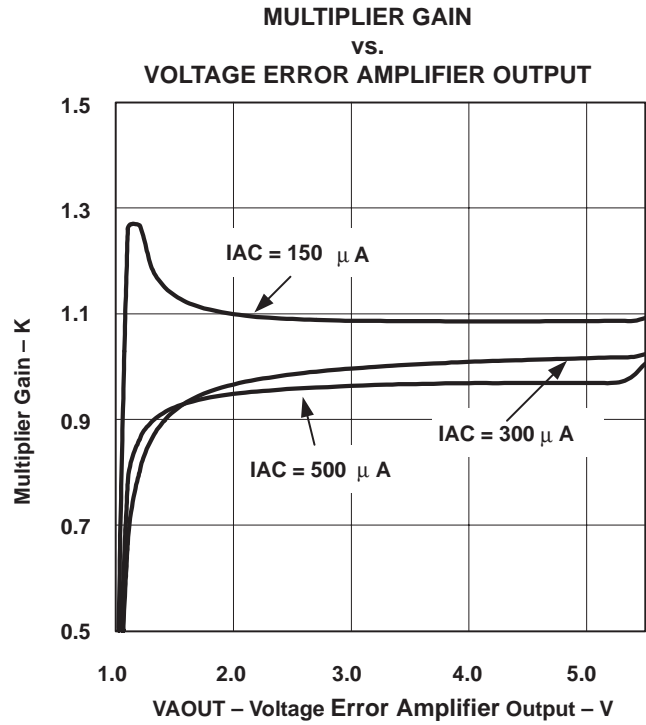


Figure 11

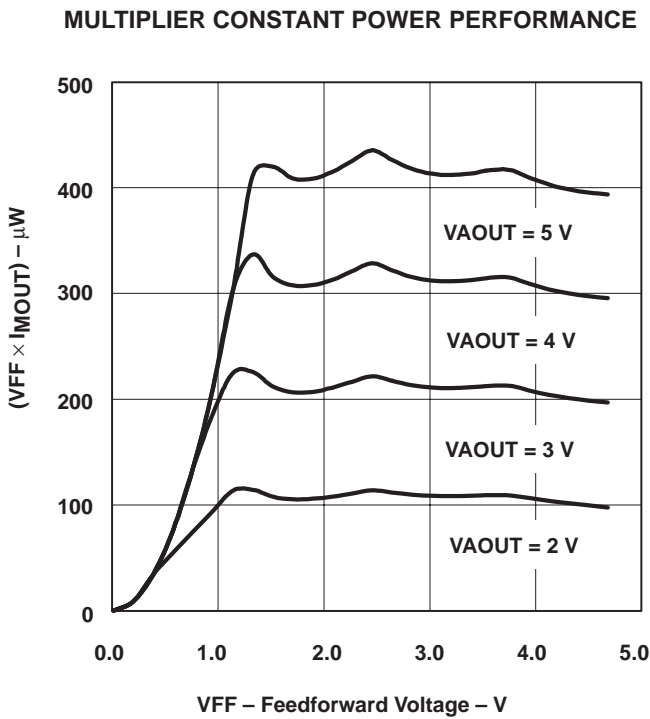


Figure 12

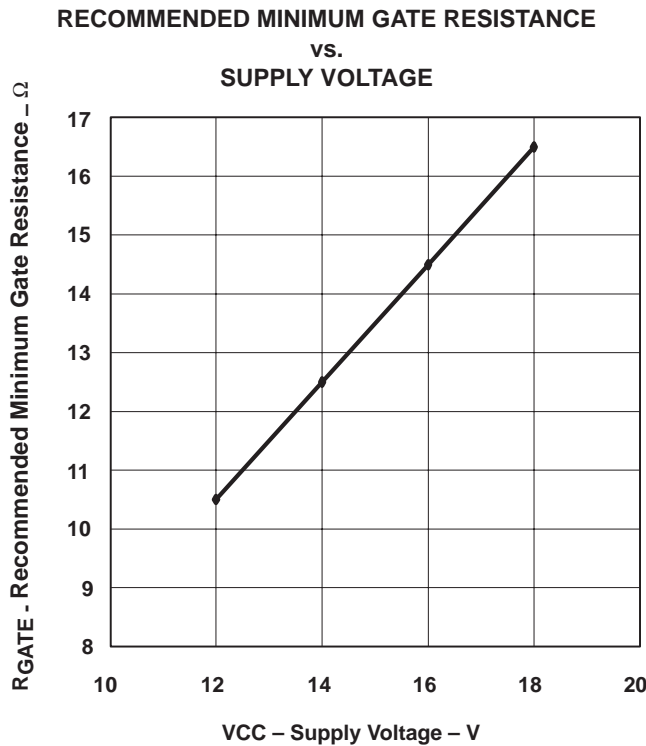


Figure 13



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